

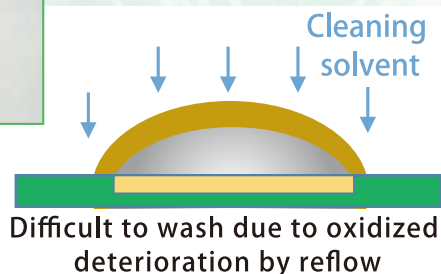
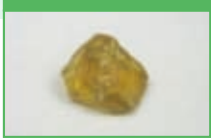
Washable Lead Free Solder Paste

Excellent wash-ability and less void generation.Suitable for Power transistor soldering.

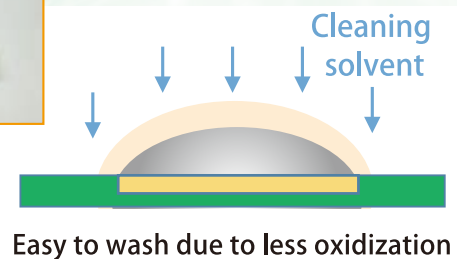
ECOHAT

Superior washing property with modified rosin

Conventional flux



New flux



Wash-ability improvement by flux optimization

Excellent washing

CSP $\varnothing 0.4\text{mm}$

Before washing



After washing



Large Area ($10 \times 10\text{mm}$)

Before washing



After washing



Test condition

- Cleaning Solvent :Glycol ether series
- Cleaning condition :70°C/20min.
- Rinse :Glycol ether series
- Rinse Condition :25°C/2min.

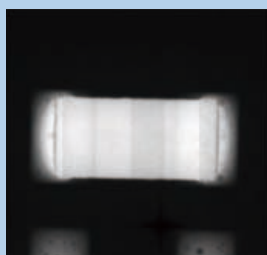
High reliability achievement with excellent Wash-ability

Less void generation

Chip

Heatsink

Void occurrence
X-ray analysis



Test condition

- Component :3216 chip resistance, Heatsink(7x7mm Ni-finish)
- Substrate :FR-4
- Paste thickness :200 μm

Secure joining reliability with less void generation